Product End-of-Life Disassembly Instructions

Product Category: Desktops
Marketing Name / Model [List multiple models if applicable.]
HP EliteDesk 800 G6 Small Form Factor PC; HP EliteDesk 800 G8 Small Form Factor PC; HP Elite SFF 600 G9 Desktop PC; HP Elite SFF 800 G9 Desktop PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact HP's Sustainability Contact.

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	☒ Main board (MB) PCB ☒ Solid state drive (SSD) PCB ☐ Wireless WAN module (WWAN) PCB ☐ Touch module PCB ☒ HDD PCB ☒ Memory PCB ☒ Power supply PCB ☒ External Keyboard (KB) ☒ External Mouse ☐ Others: _____________	7
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	☒ RTC/CMOS battery ☐ Others: _____________	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: ☐ screws ☐ snaps ☐ adhesive ☐ other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0

Item Description	**Components and parts requiring selective treatments**	**Quantity of items included in product**
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	☐ Panel LCD	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	☒ Power Supply capacitor(s) or condenser(s)	1
External electrical cables and cords	☒ AC power cord ☐ Audio, video or data cables ☐ Other: _________	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Hexagon Screw Driver T-15	T-15
Crisscross Screw Driver PH1	PH1
Soldering Iron	

3.0 Product Disassembly Process

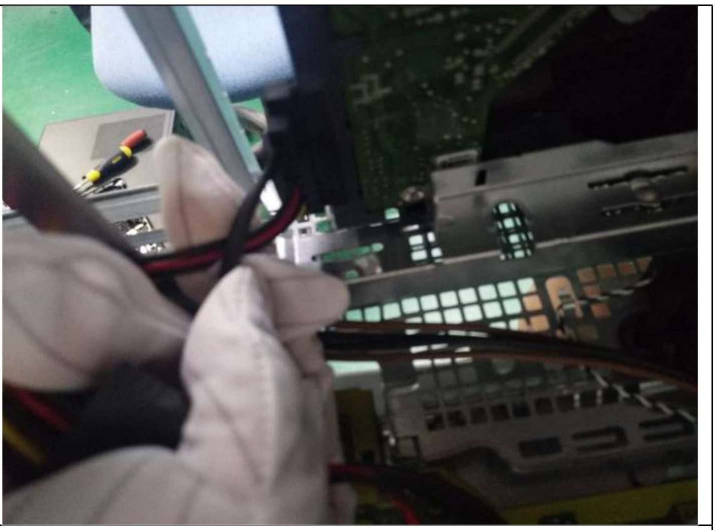
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

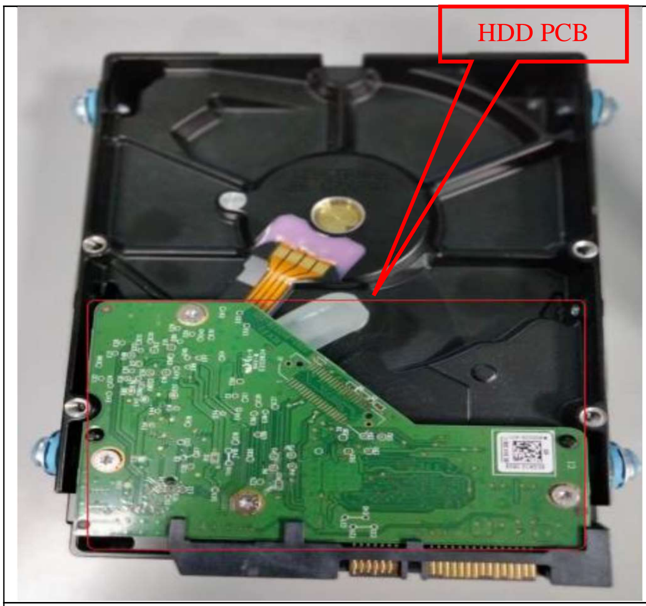
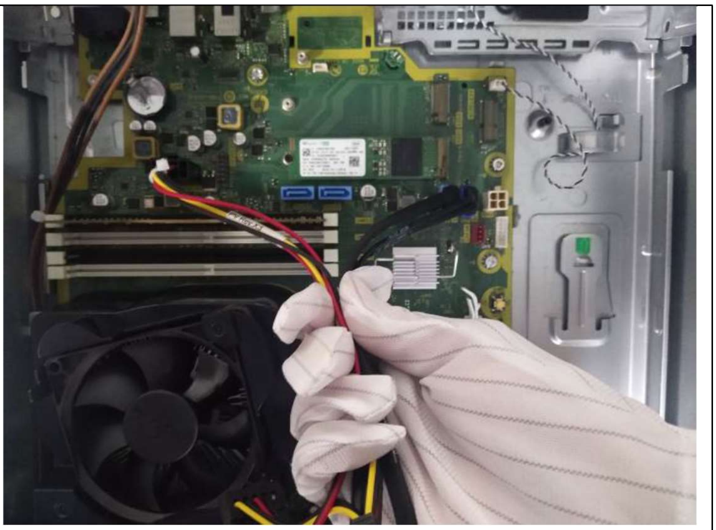
1. Use T-15 screw driver to loose thumb screw and remove access panel.
2. Disconnect ODD power cable and ODD SATA cable from ODD.
3. Press the ODD’s latch on ODD cage
4. Remove the ODD from ODD cage
5. Remove Front Bezel from chassis
6. Disconnect HDD power cable and HDD SATA cable from HDD.
7. Remove the driver cage from Chassis
8. Use T-15 screwdriver to loose the screws of HDD
9. Remove HDD from HDD cage
10. Disconnect all cables from MB
11. Remove the Fan duct from cooler
12. Disconnect Cooler Fan cable from MB
13. Use T-15 screw driver to loose the cooler screws and remove cooler from MB
14. Use T-15 screw driver to loose the screws and remove the fan
15. Separate the fan from CPU heat sink
16. Remove memory from the MB
17. Rotate the handle and open it up
18. Remove the CPU from the board
19. Remove SSD M.2 Card
20. Remove WLAN M.2 Card
21. Remove the battery from the system board
22. Use T-15 screw driver to loose the screws of MB from board
23. Remove MB from chassis
24. Remove speaker from Chassis
25. Use T-15 screw driver to loose the screws of PSU
26. Press the PSU’s latch on chassis
27. Remove the PSU from chassis
28. Remove the screws covered
29. Remove PSU cover
30. Use PH1 screw driver to remove FG screw
31. Disconnect fan connector and inlet connector
32. Loose screws and remove PCB from case
33. Loose screws and remove PSU fan
34. Use Soldering Iron to remove Ele-Cap from PCBA

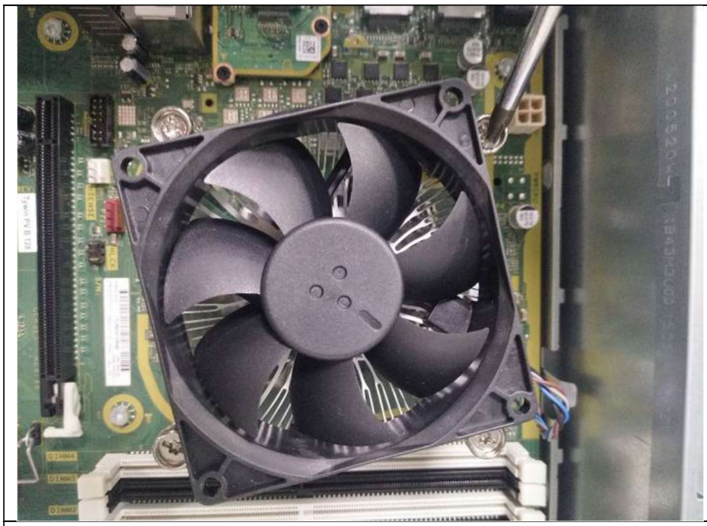
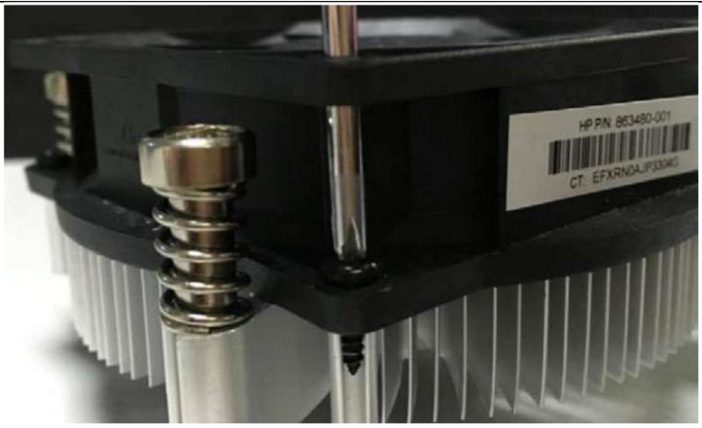
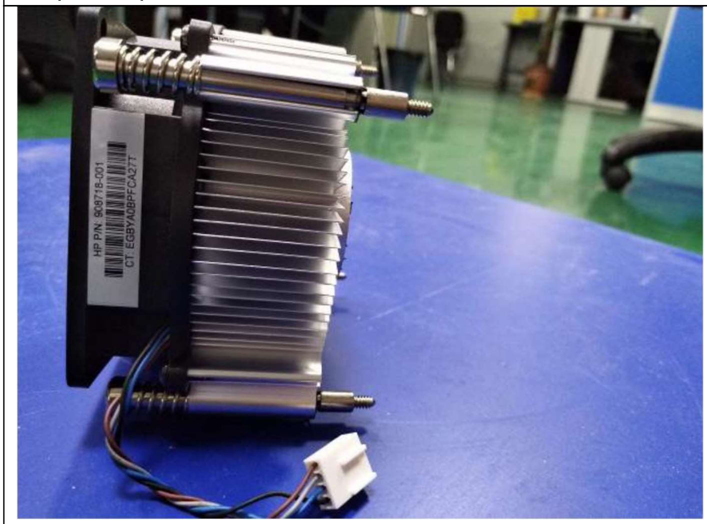
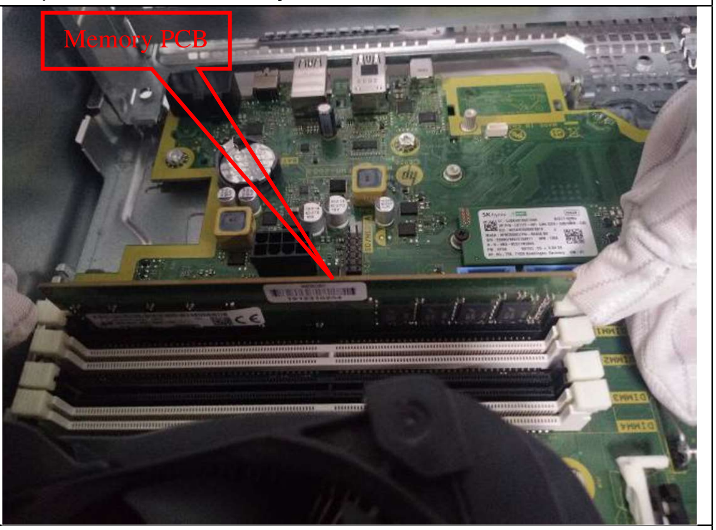
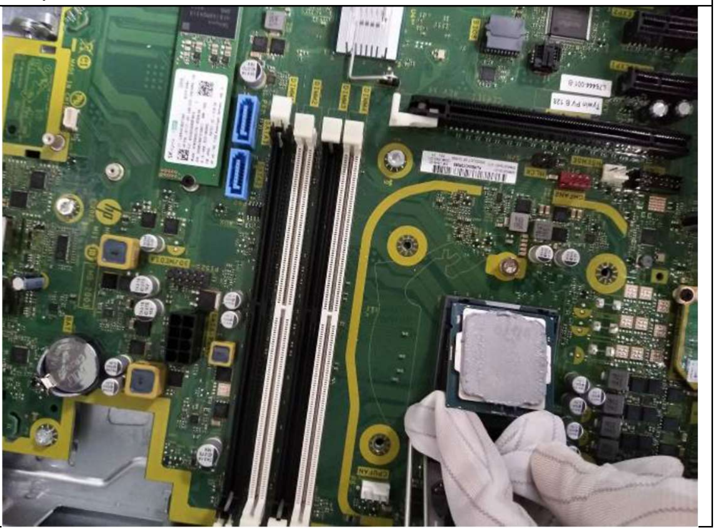
25. Press the PSU’s latch on chassis3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: End-of-Life Product Disassembly Instructions (hp.com)

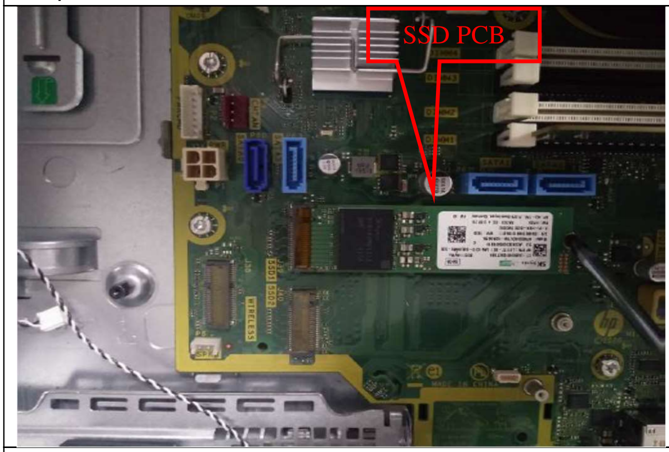
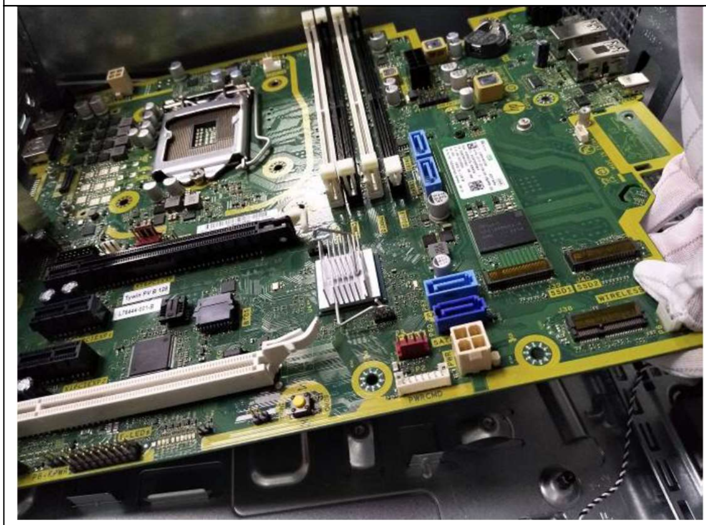
Step1 Use T-15 screw driver to Loose thumb screw and remove access panel.	Step2 Disconnect ODD power cable and ODD SATA cable from ODD.

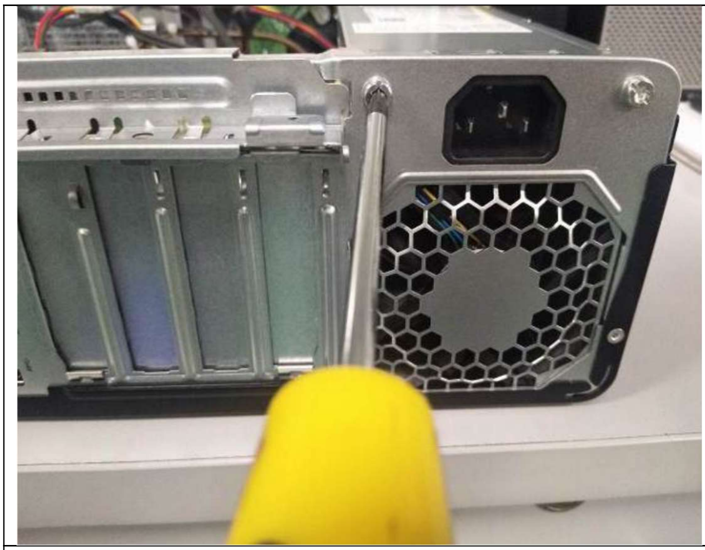
	
Step3 Press the ODD's latch on ODD cage	Step4 Remove the ODD from ODD cage
	
Step5 Remove Front Bezel from chassis	Step6 Disconnect HDD power cable and HDD SATA cable from HDD.

	
Step7 Remove the driver cage from Chassis	Step8 Use T-15 screw driver to loose the screws of HDD
	
Step9 Remove HDD from HDD cage	Step10 Disconnect all cables from MB

 	
Step 11 Remove the Fan Duct from cooler	Step12 Disconnect Cooler Fan cable from MB
	
Step13 Use T-15 screw driver to loose the cooler screws and remove cooler from MB	Step14 Use T-15 screwdriver to loose the screws and remove the fan

	
Step15 Separate the fan from CPU heat sink	Step16 Remove memory from the MB
	
Step17 Rotate the handle and open it up	Step18 Remove the CPU from the board
	

Step19 Remove SSD M.2 Card	Step20 Remove WLAN M.2 Card
	
Step21 Remove the battery from the system board	Step22 Use T-15 screwdriver to loose the screws of MB from board
	
Step23 Remove MB from chassis	Step24 Remove speaker from Chassis
	
Step25 Use T-15 screwdriver to loose the screws of PSU	Step26 Press the Power supply's latch on chassis

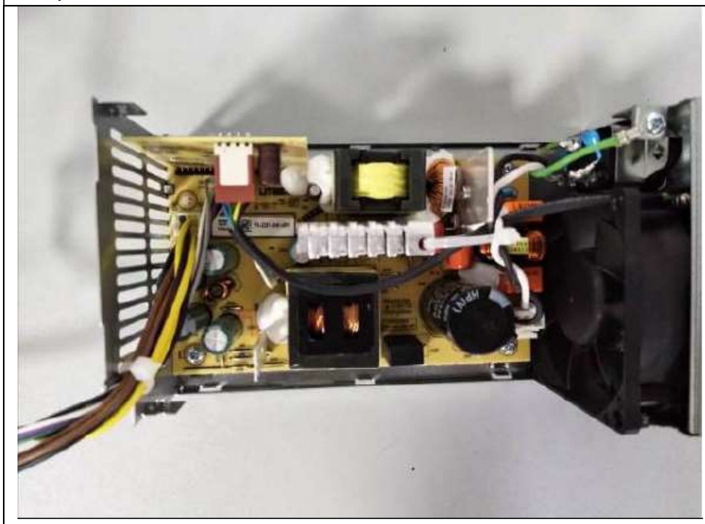


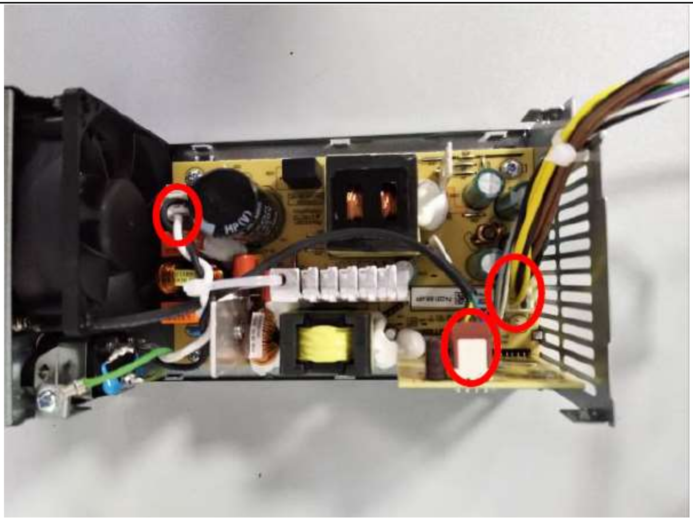
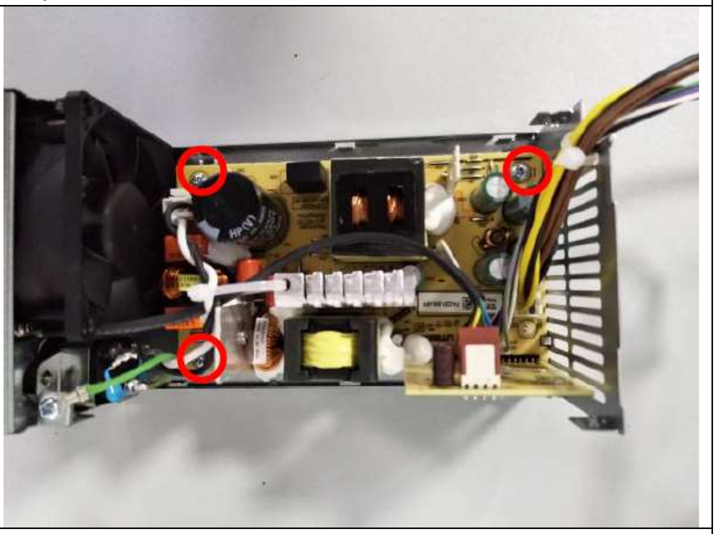
Step27 Remove the Power supply from chassis

Step28 Remove screws covered

Step29 Remove PSU cover

Step30 Use PH1 screw driver to remove FG screw



Step31 Disconnect fan connector and inlet connector	Step32 Loose screws and remove PCB from case
	
Step33 Loose screws and remove PSU fan	Step34 Heat the solder of the Ele-Cap of greater than 2.5cm in diameter or height and Remove it from PCBA